



Material Content Data Sheet



Sales Product Name		BFP 183 E7764		Issued		19. July 2018		
MA#		MA001617930						
Package		PG-SOT143-4-1		Weight*		11.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.02		163	
	non noble metal	tin	7440-31-5	0.000	0.00		42	
	inorganic material	silicon	7440-21-3	0.016	0.14	0.16	1408	1613
leadframe	non noble metal	nickel	7440-02-0	1.673	15.12		151217	
	non noble metal	iron	7439-89-6	2.310	20.88	36.00	208824	360041
wire	noble metal	gold	7440-57-5	0.016	0.15	0.15	1476	1476
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9438	
	inorganic material	antimonytrioxide	1309-64-4	0.157	1.42		14157	
	plastics	brominated resin	-	0.196	1.77		17696	
	plastics	epoxy resin	-	1.631	14.75		147467	
	inorganic material	silicondioxide	60676-86-0	4.437	40.11	58.99	401109	589867
leadfinish	non noble metal	tin	7440-31-5	0.217	1.96	1.96	19582	19582
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27421	27421
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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